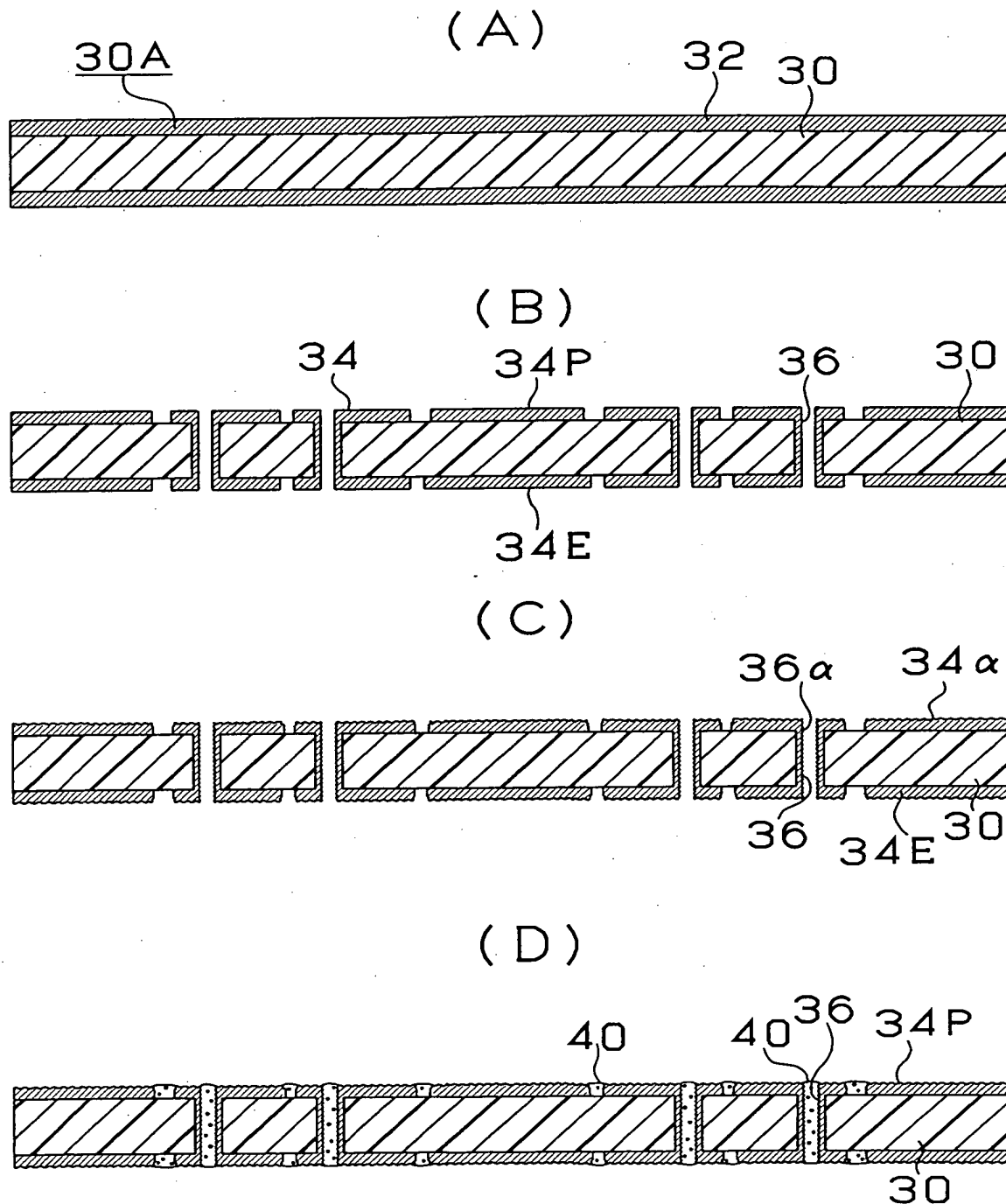
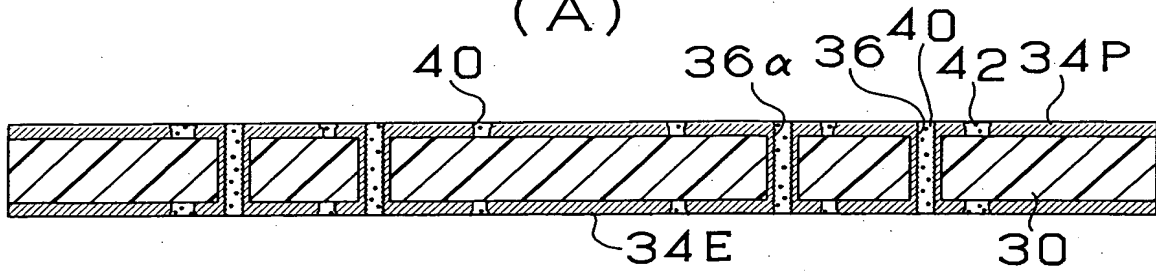


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Fig. 1

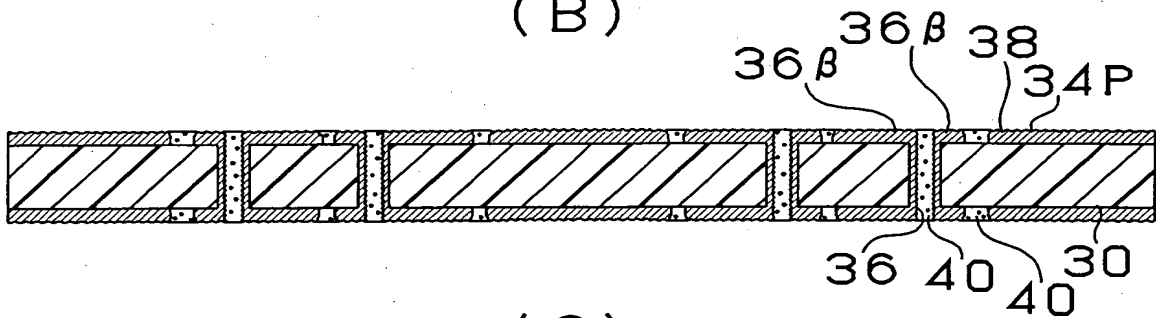


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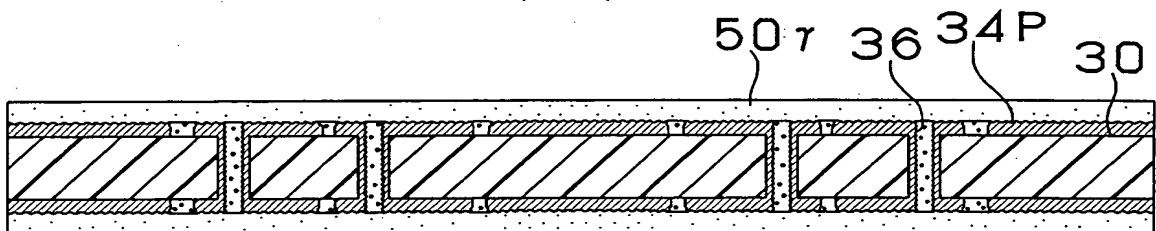
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Fig. 2
(A)



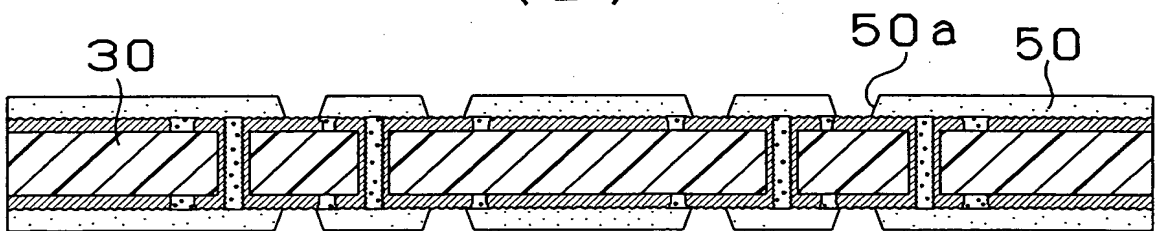
(B)



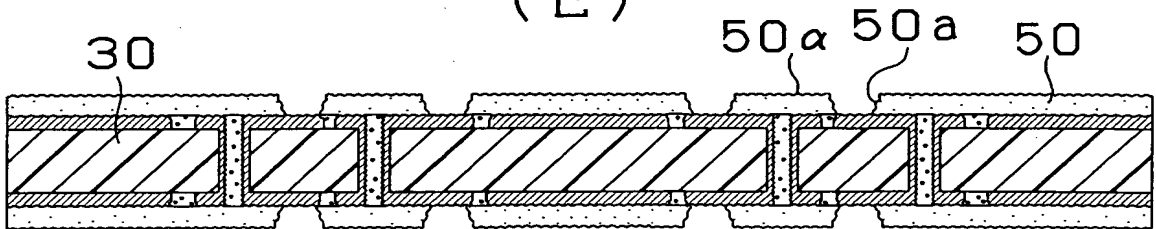
(C)



(D)



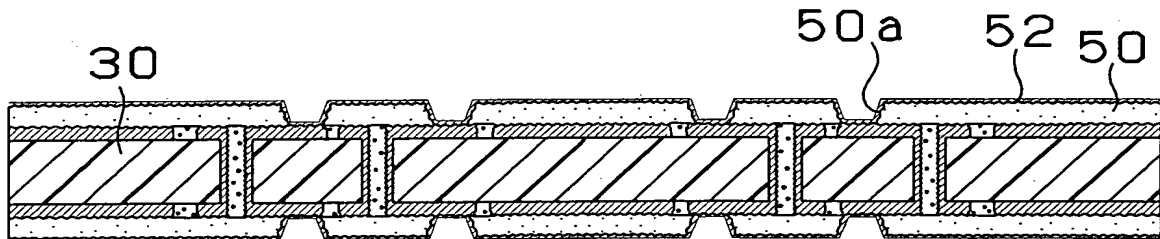
(E)



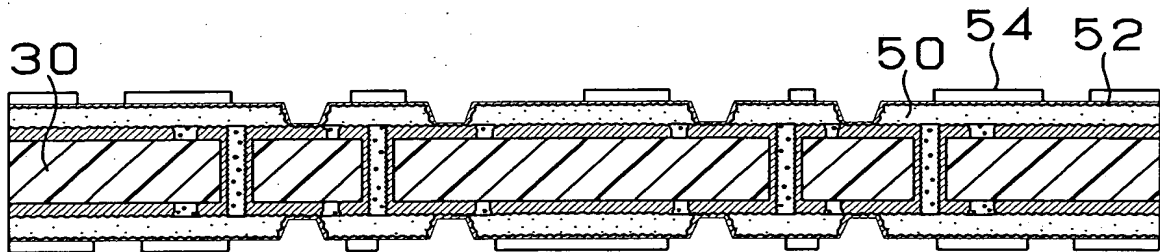
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Fig. 3

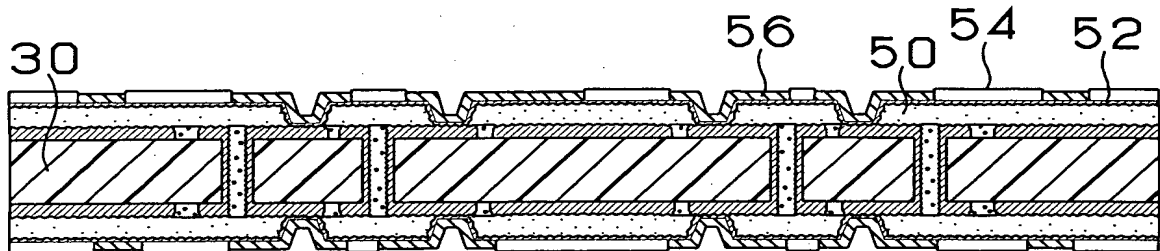
(A)



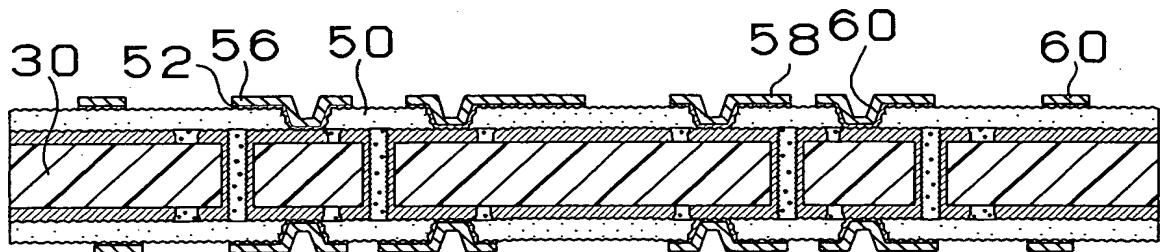
(B)



(C)

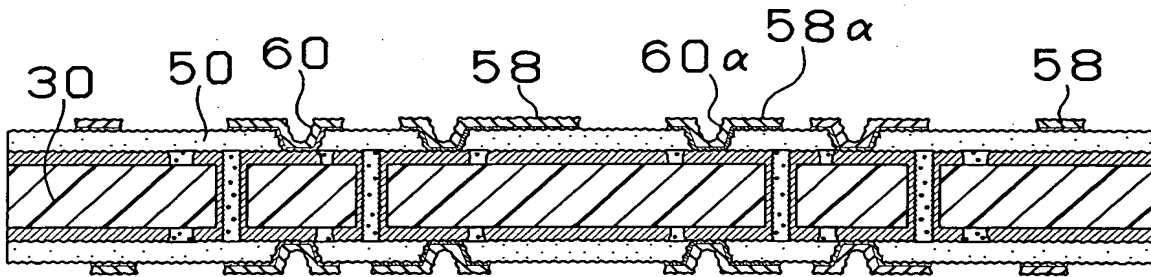


(D)

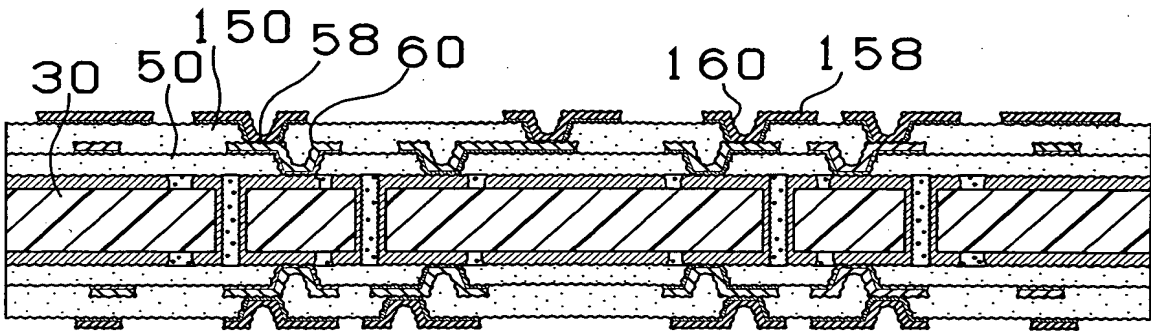


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Fig. 4

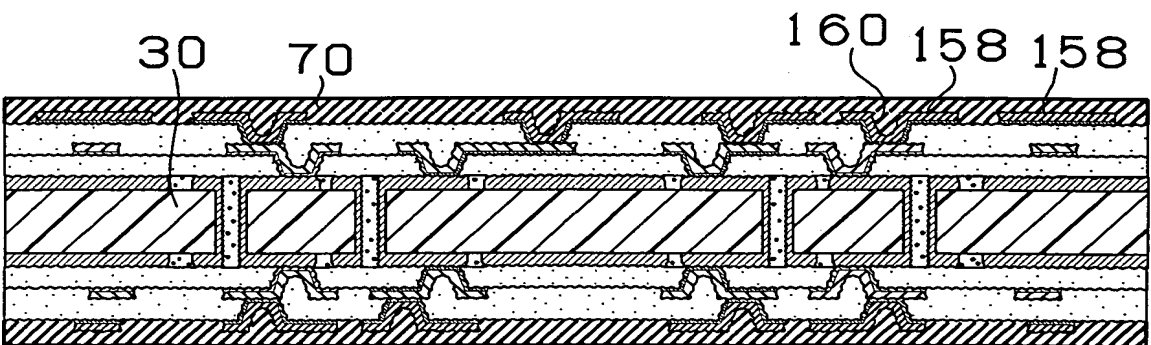
(A)



(B)

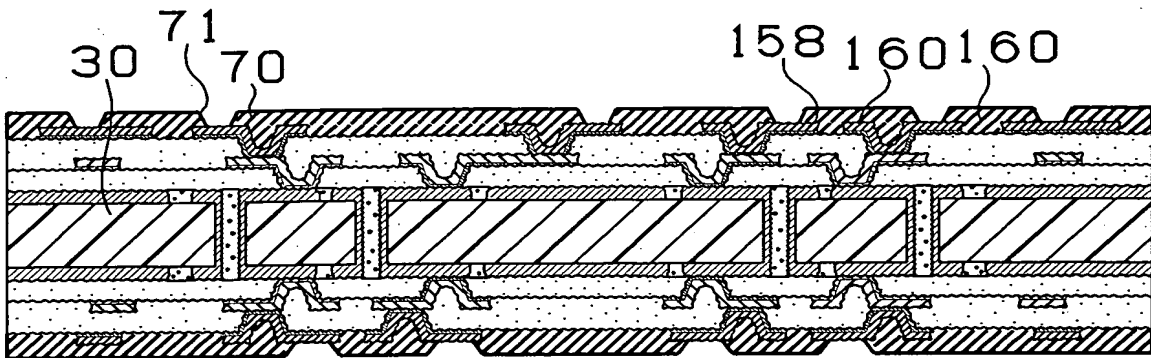


(C)



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Fig.5

(A)



(B)

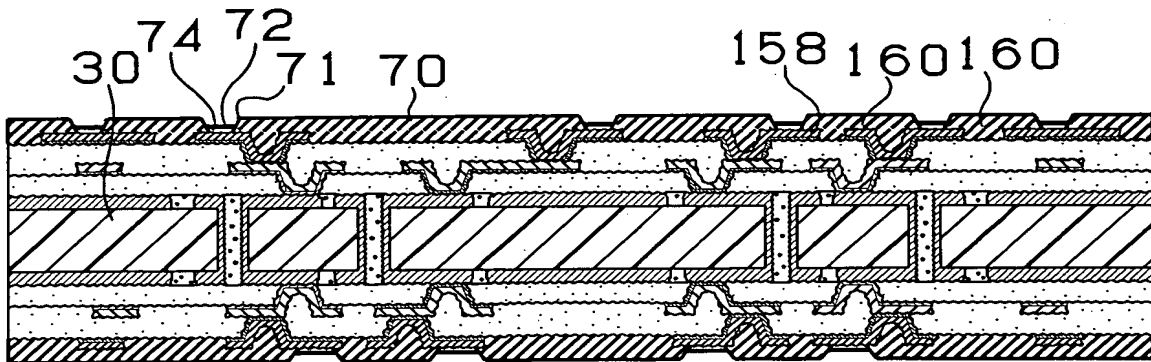
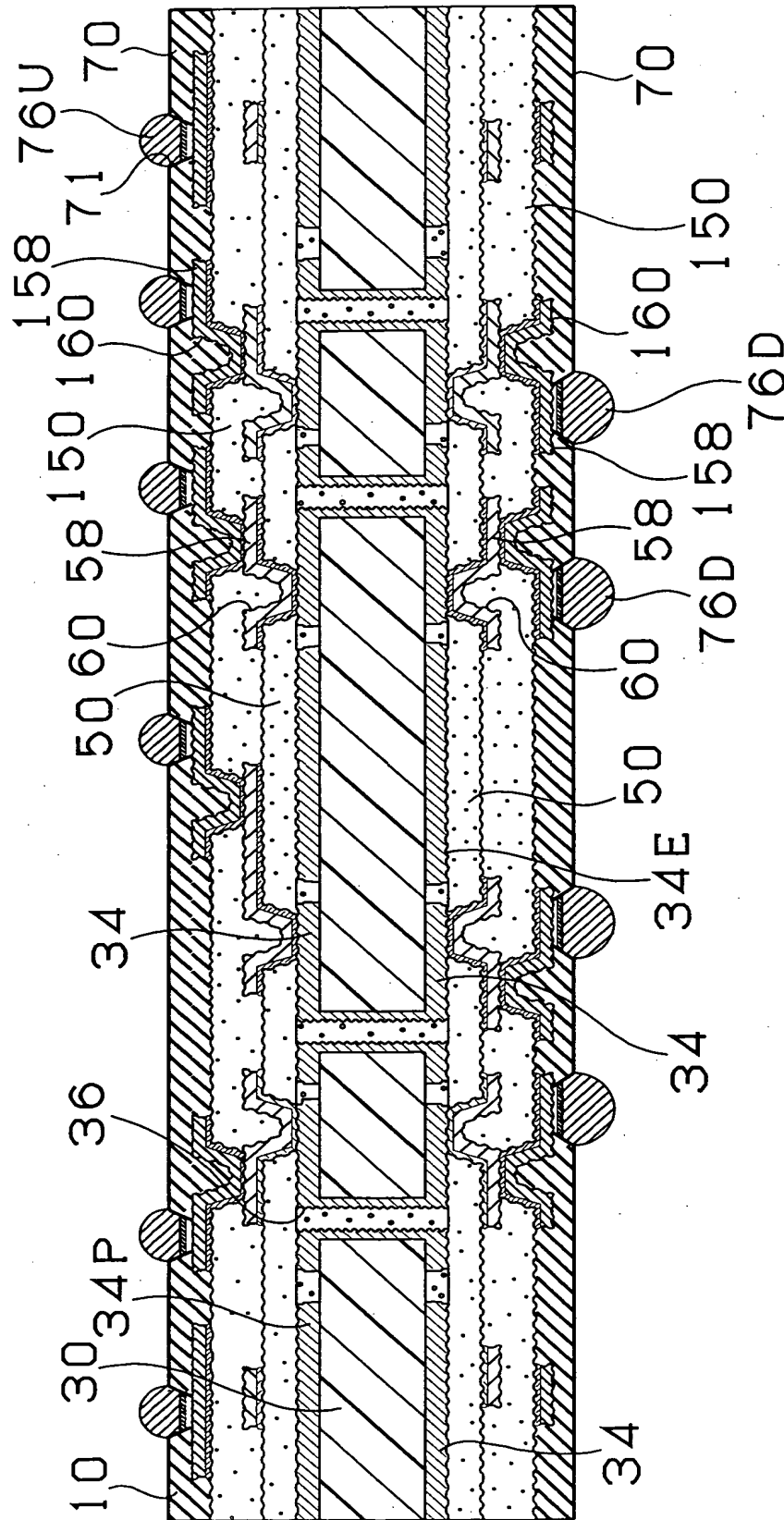
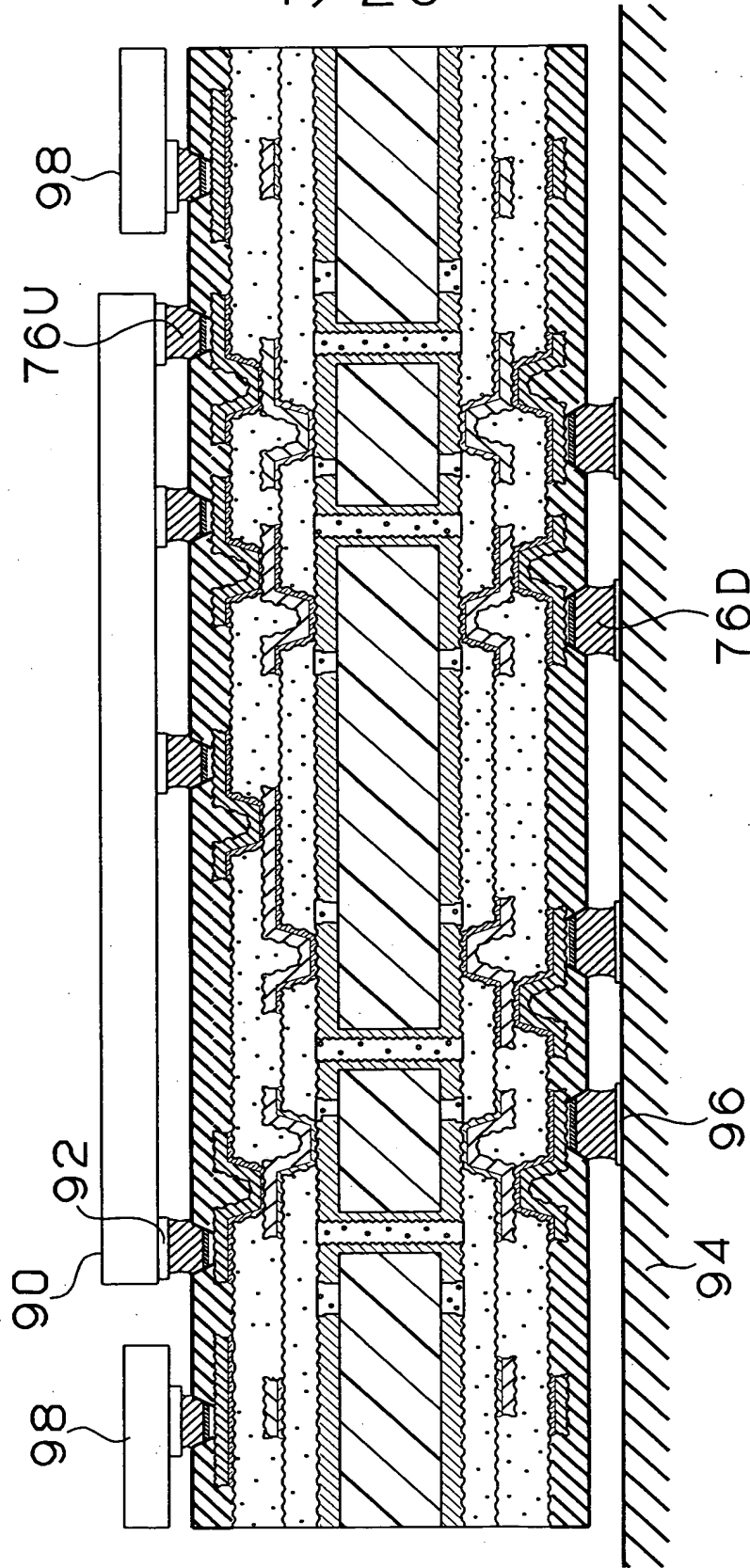


Fig. 6



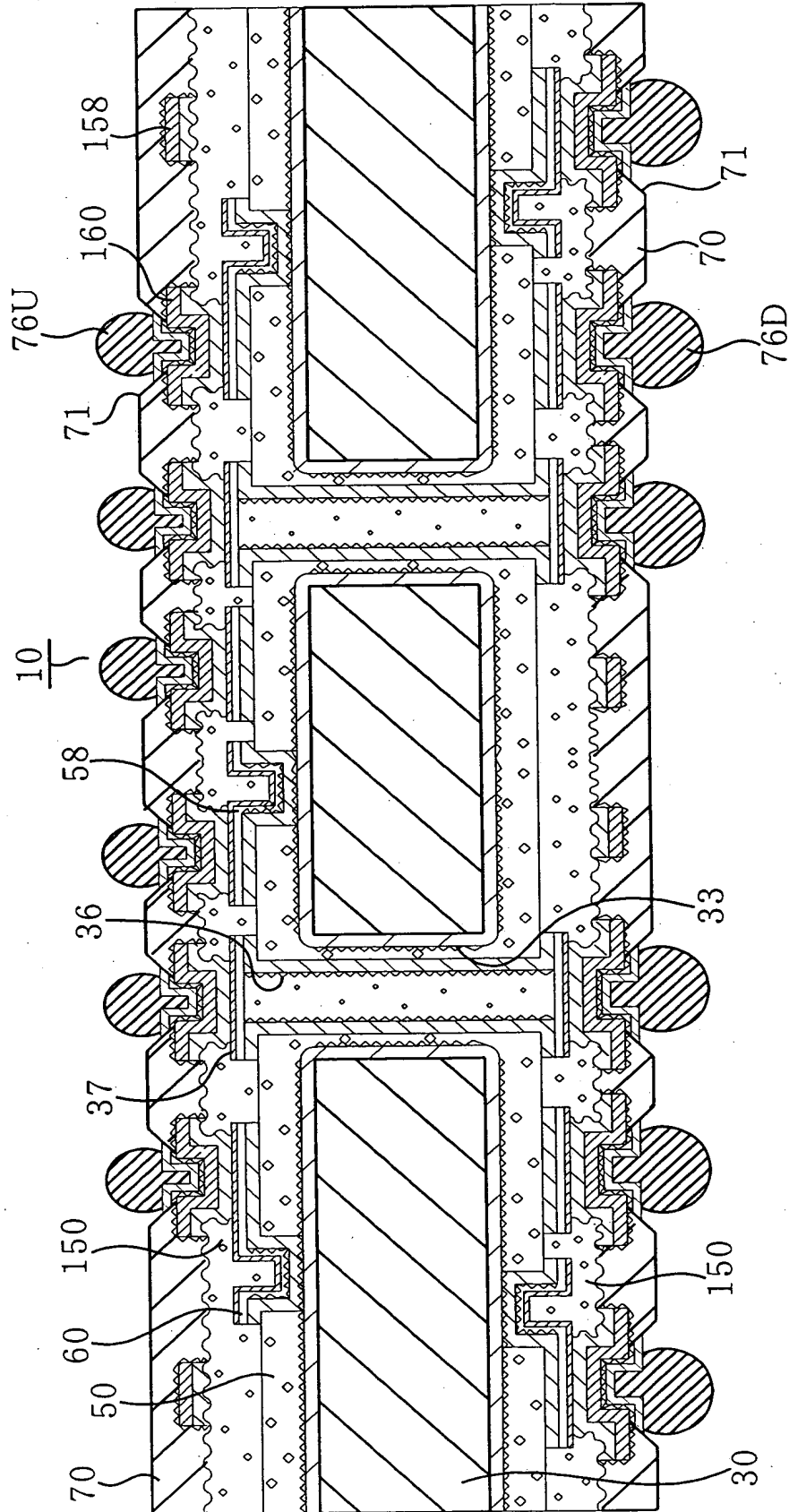
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Fig. 7



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Fig. 8



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Fig. 9

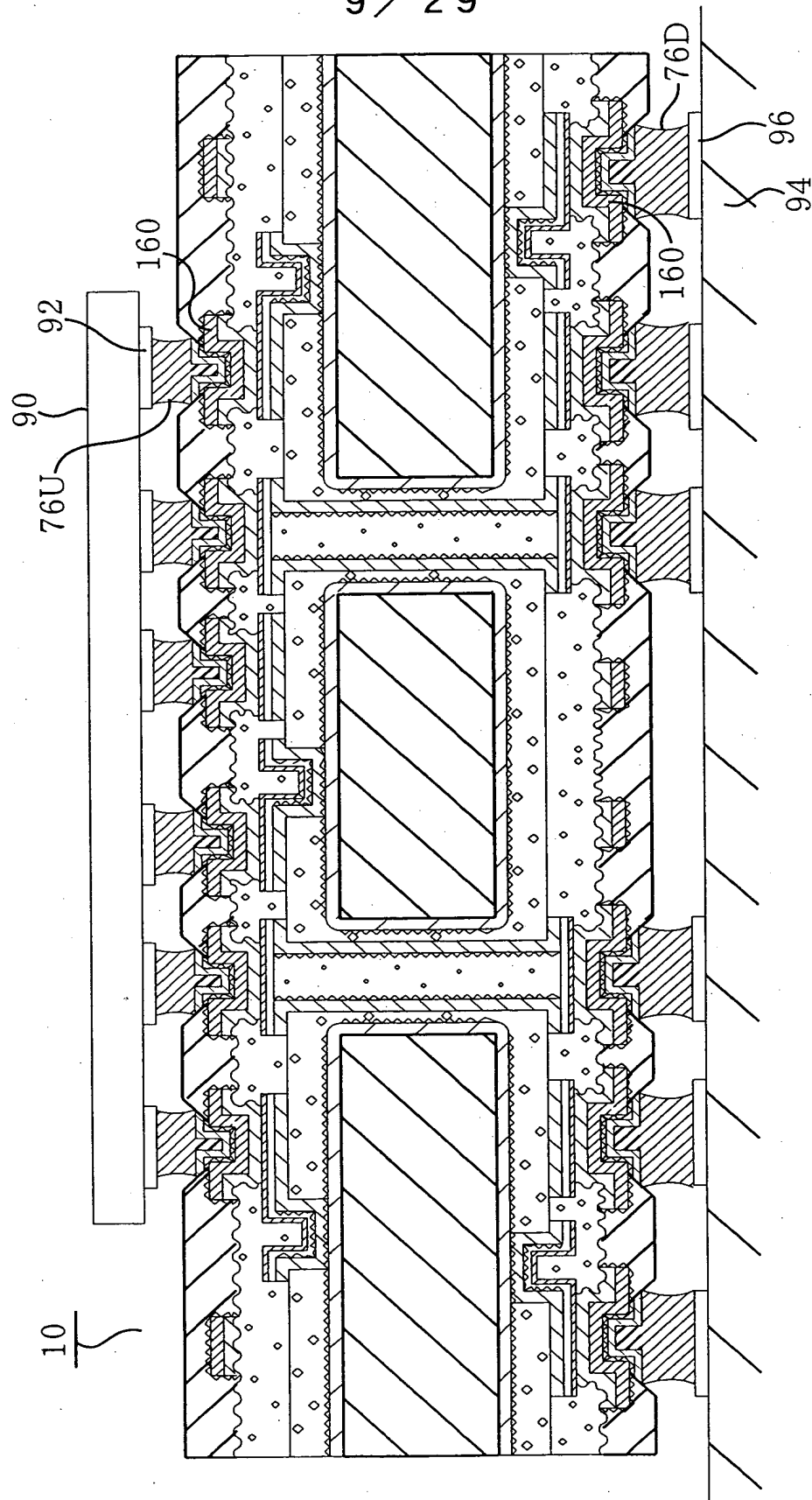
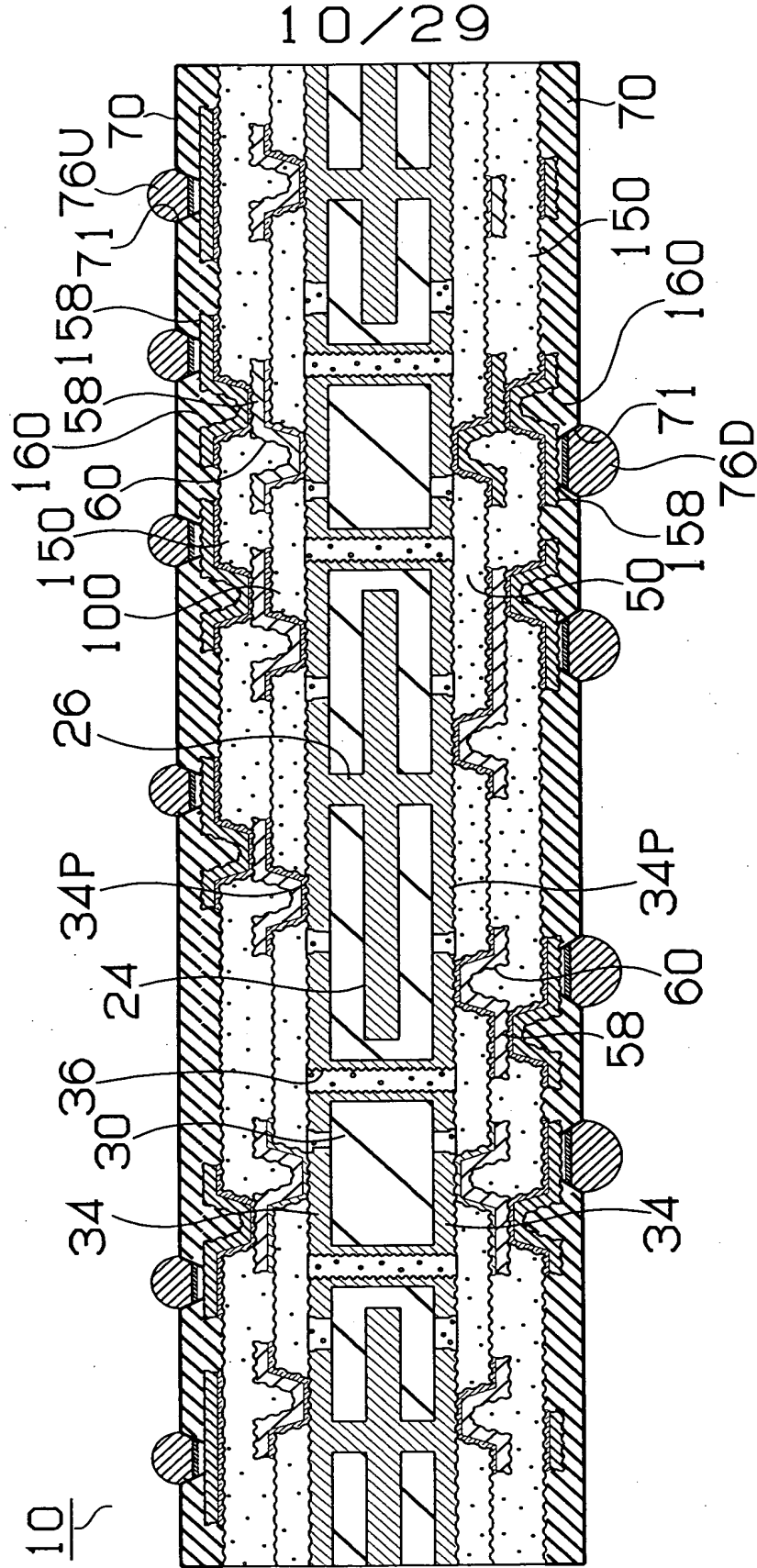
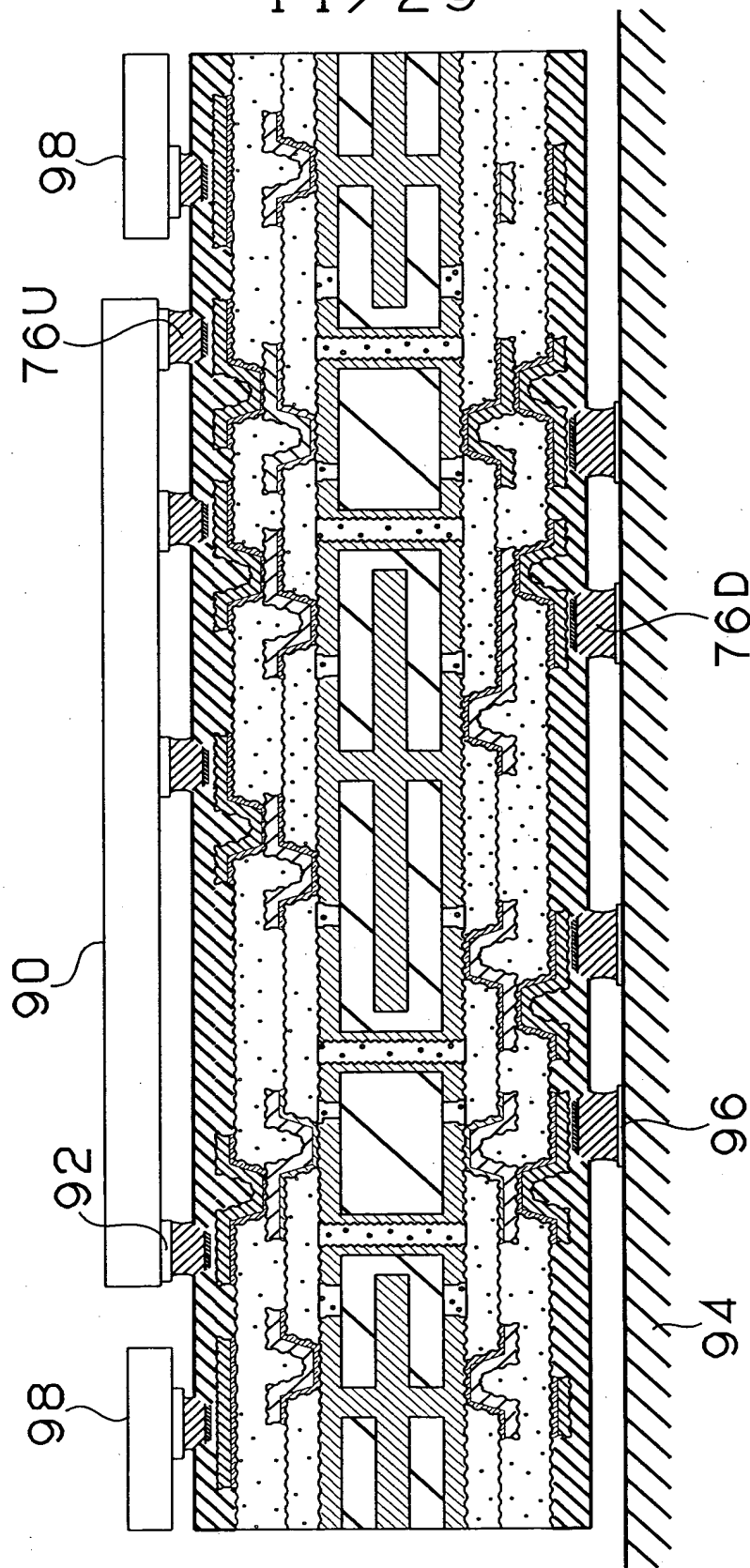


Fig. 10



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Fig. 11



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Fig.12
(A)



(B)



(C)



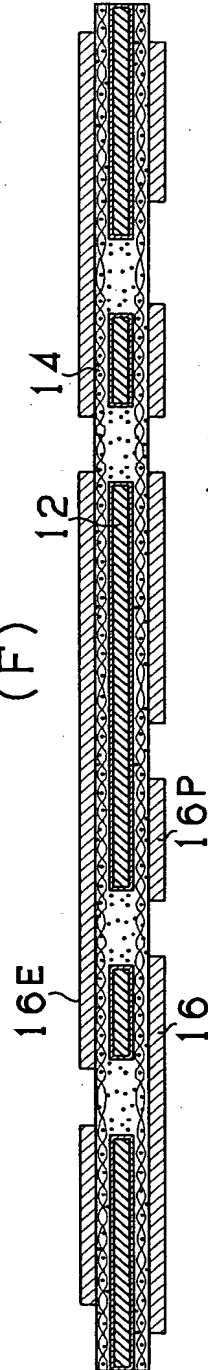
(D)



(E)



(F)



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Fig. 13
(A)

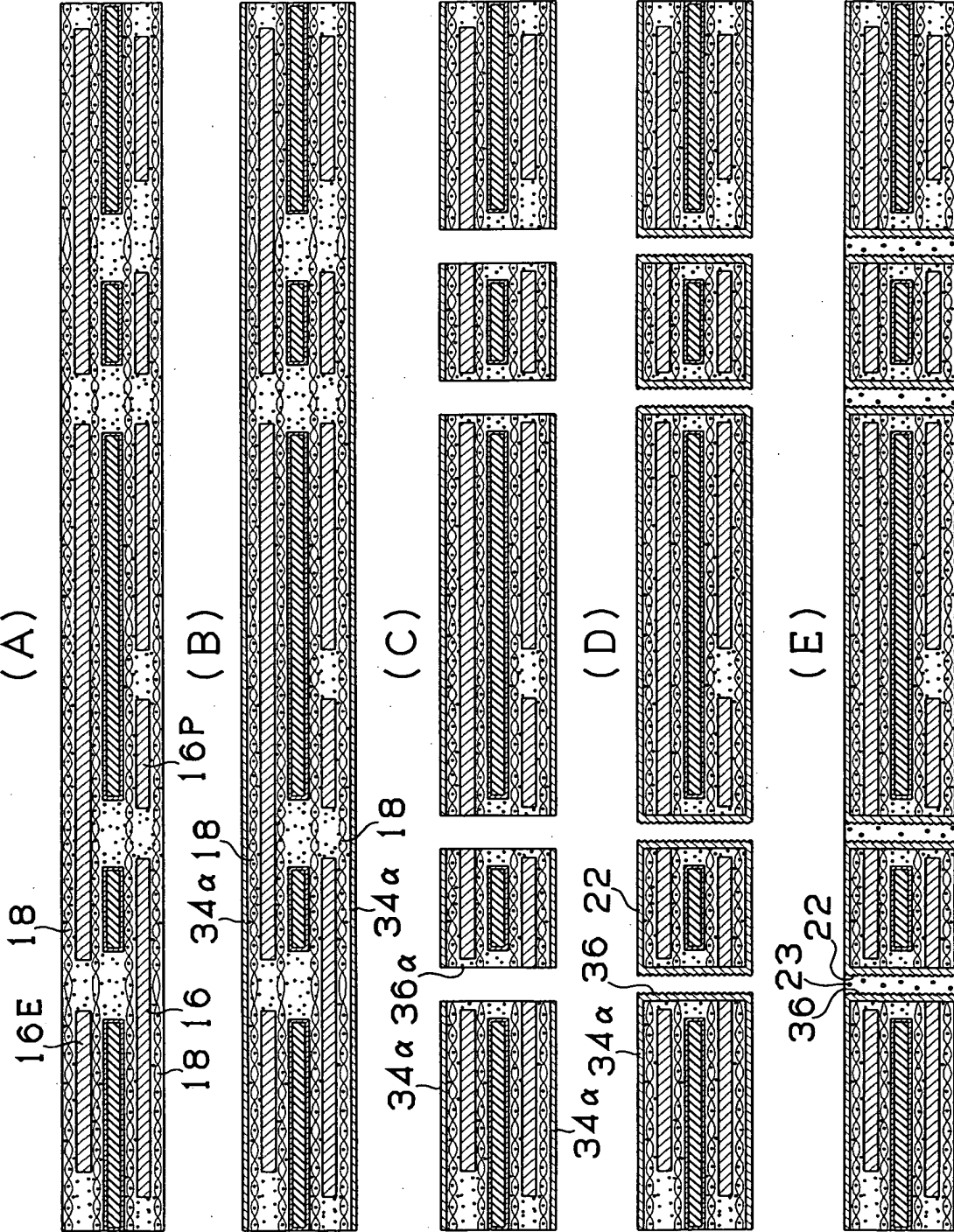
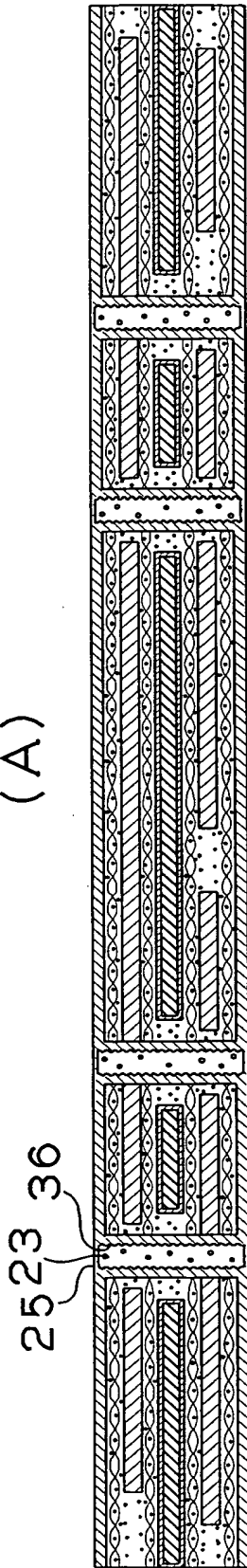
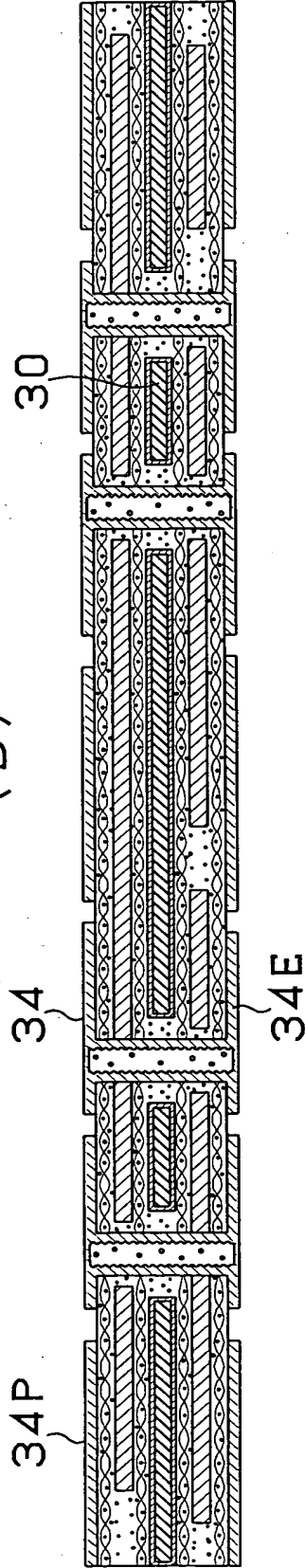


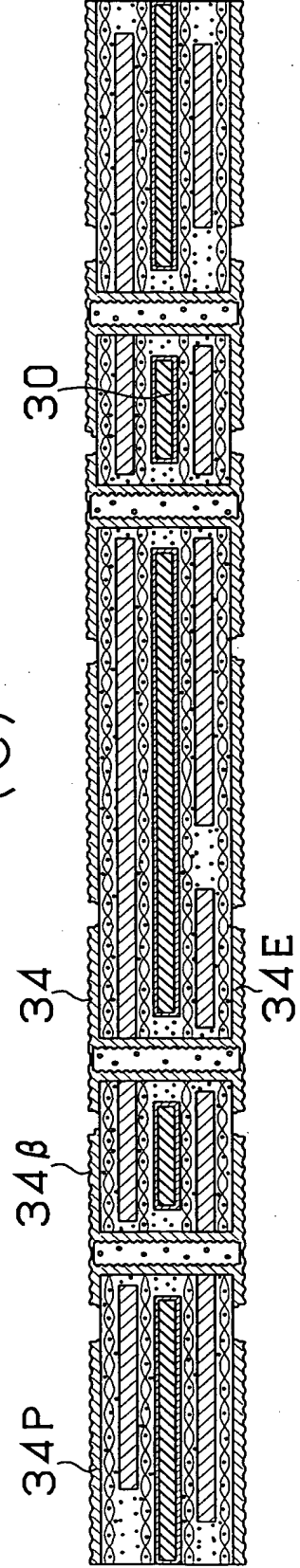
Fig. 14
(A)



(B)

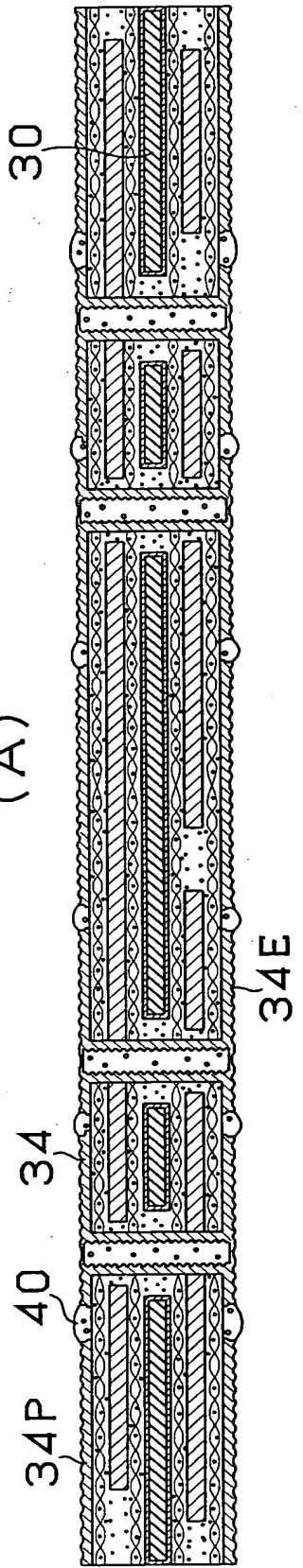


(C)

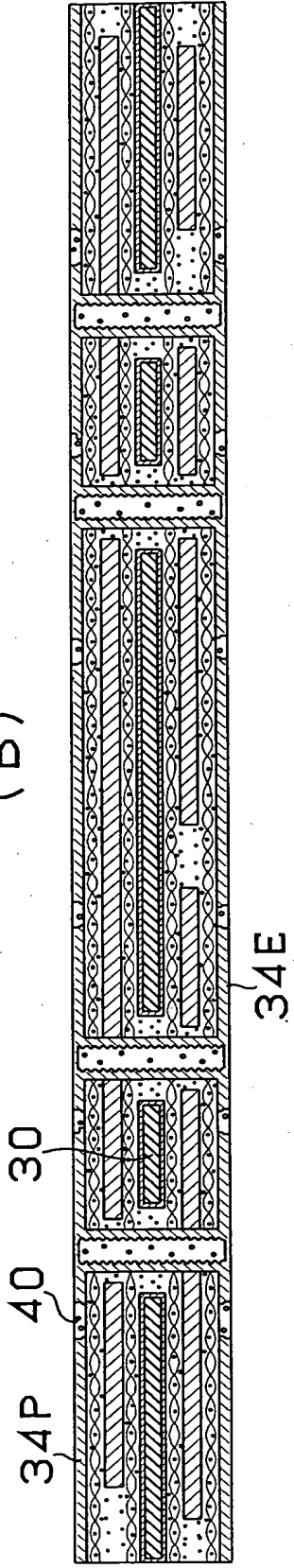


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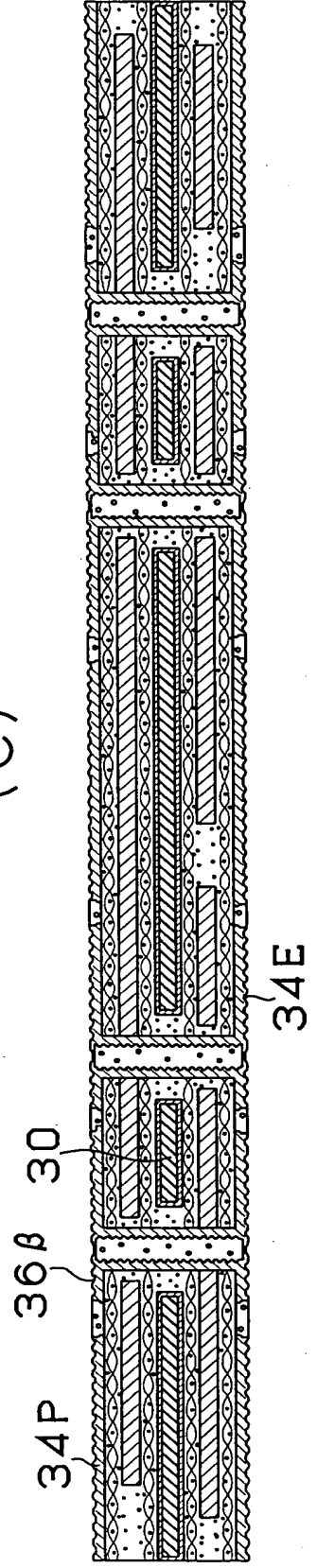
Fig. 15
(A)



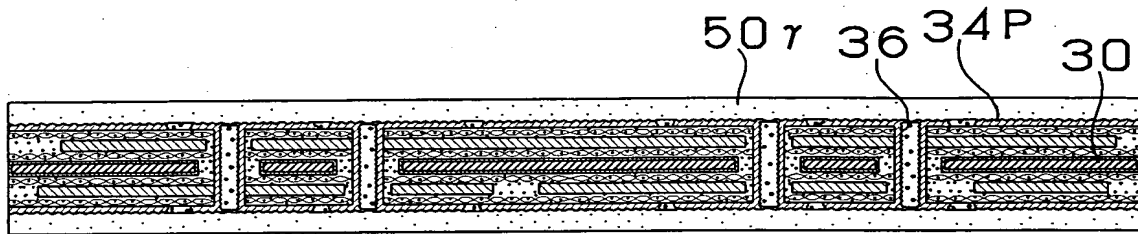
(B)



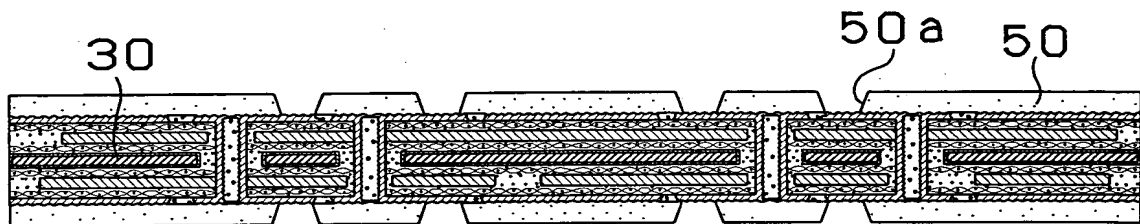
(C)



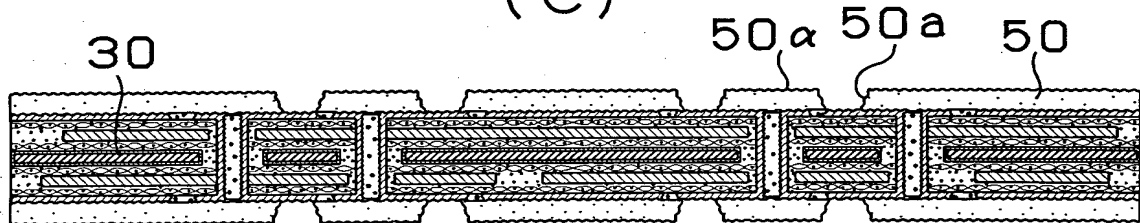
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Fig. 16
(A)



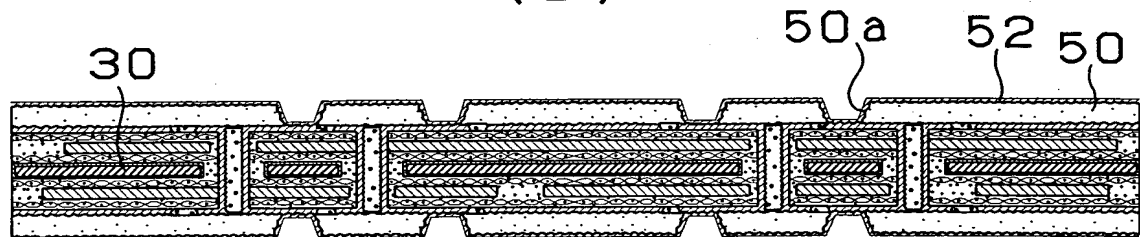
(B)



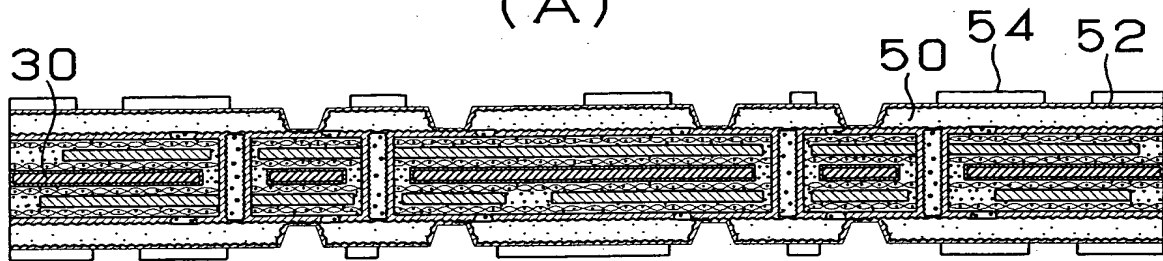
(C)



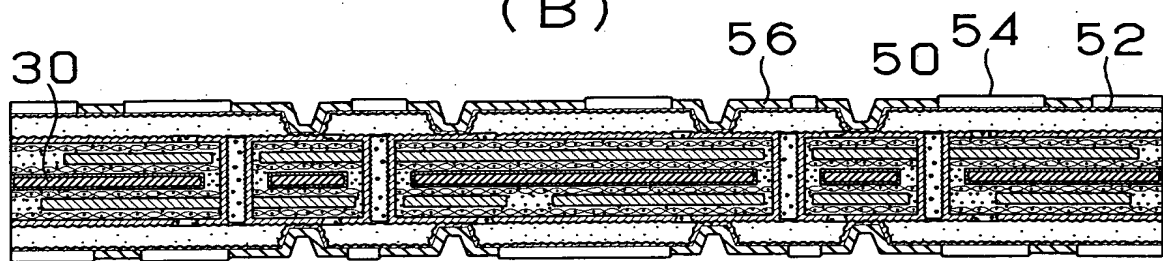
(D)



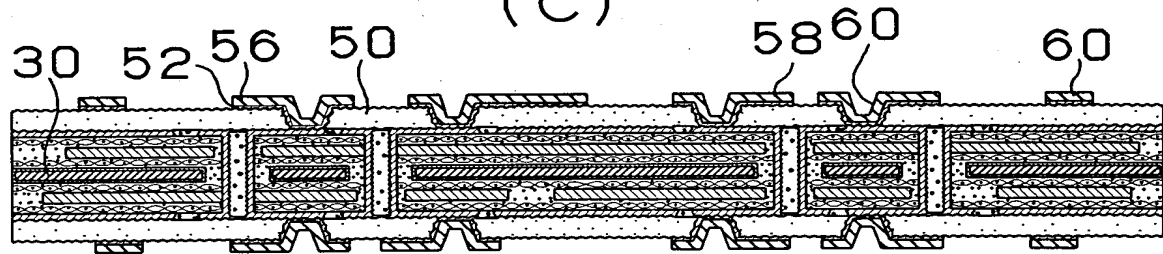
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Fig. 17
(A)



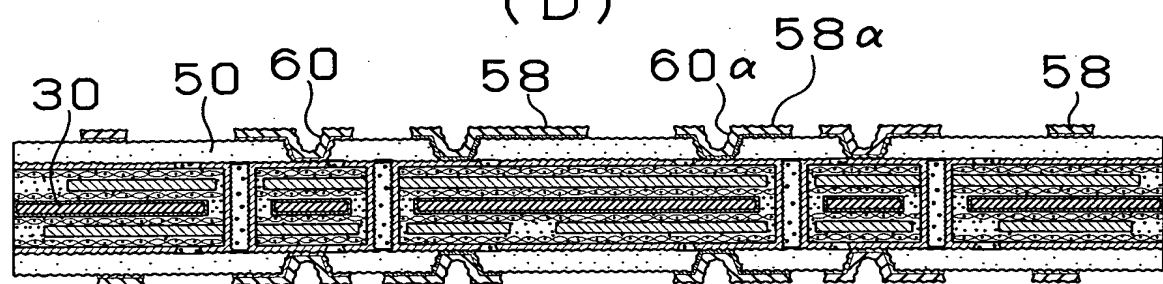
(B)



(C)



(D)



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Fig. 18
(A)

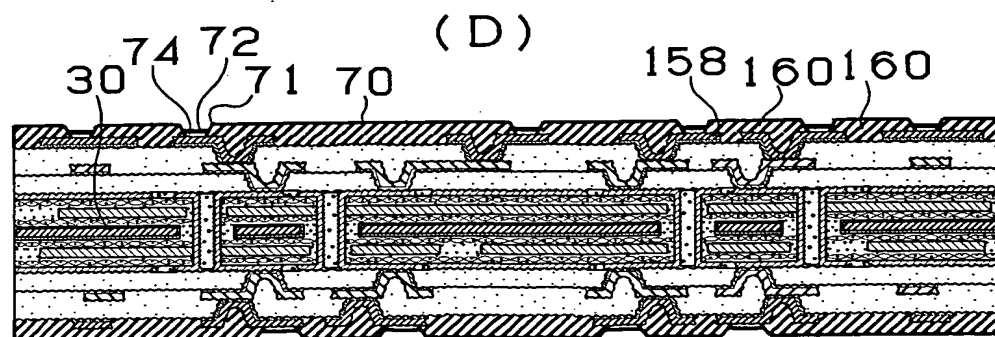
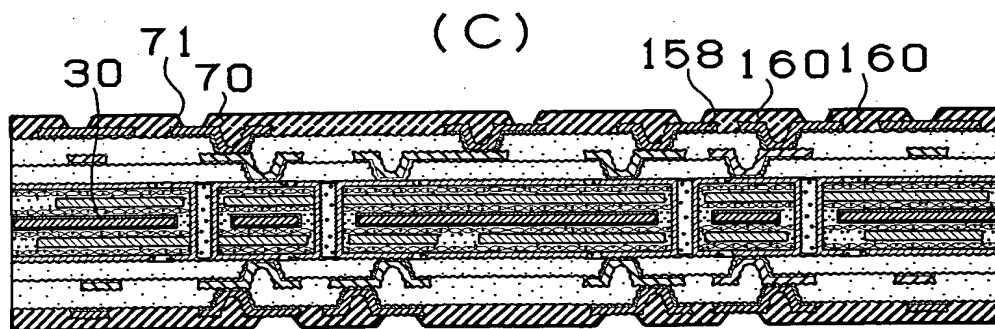
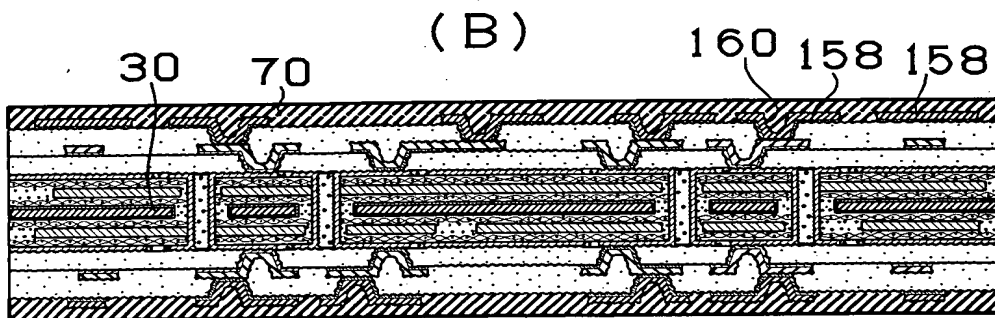
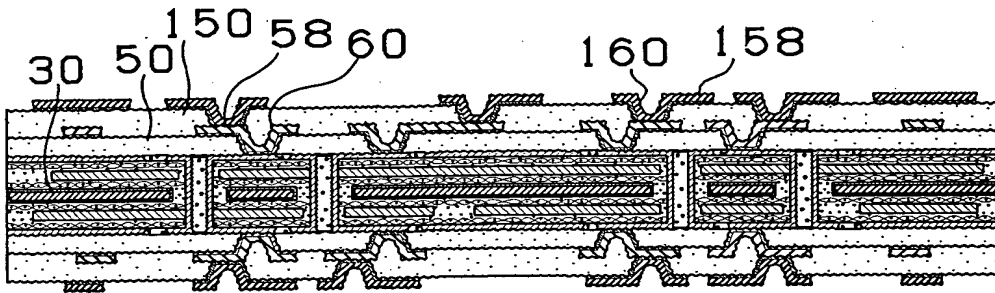
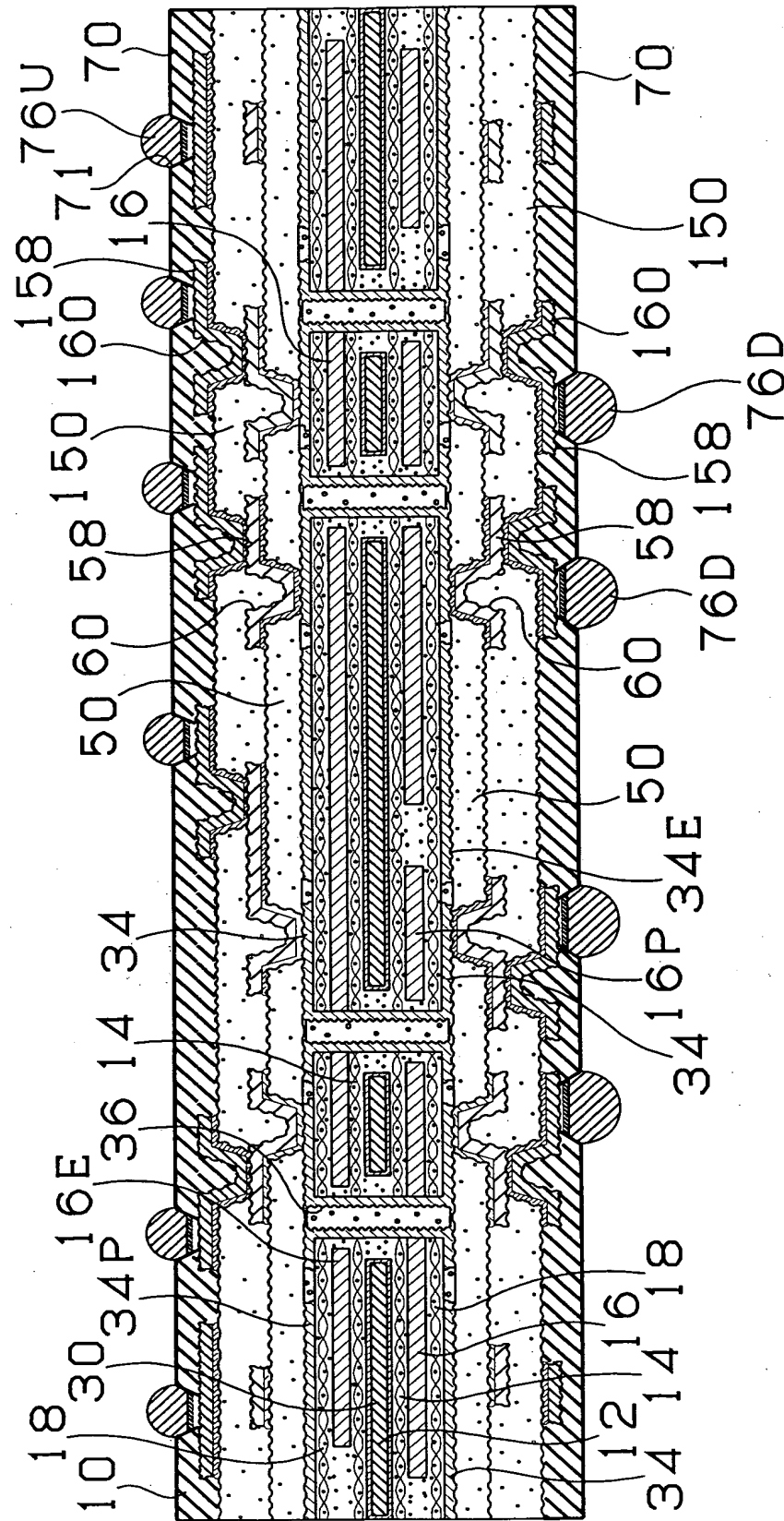
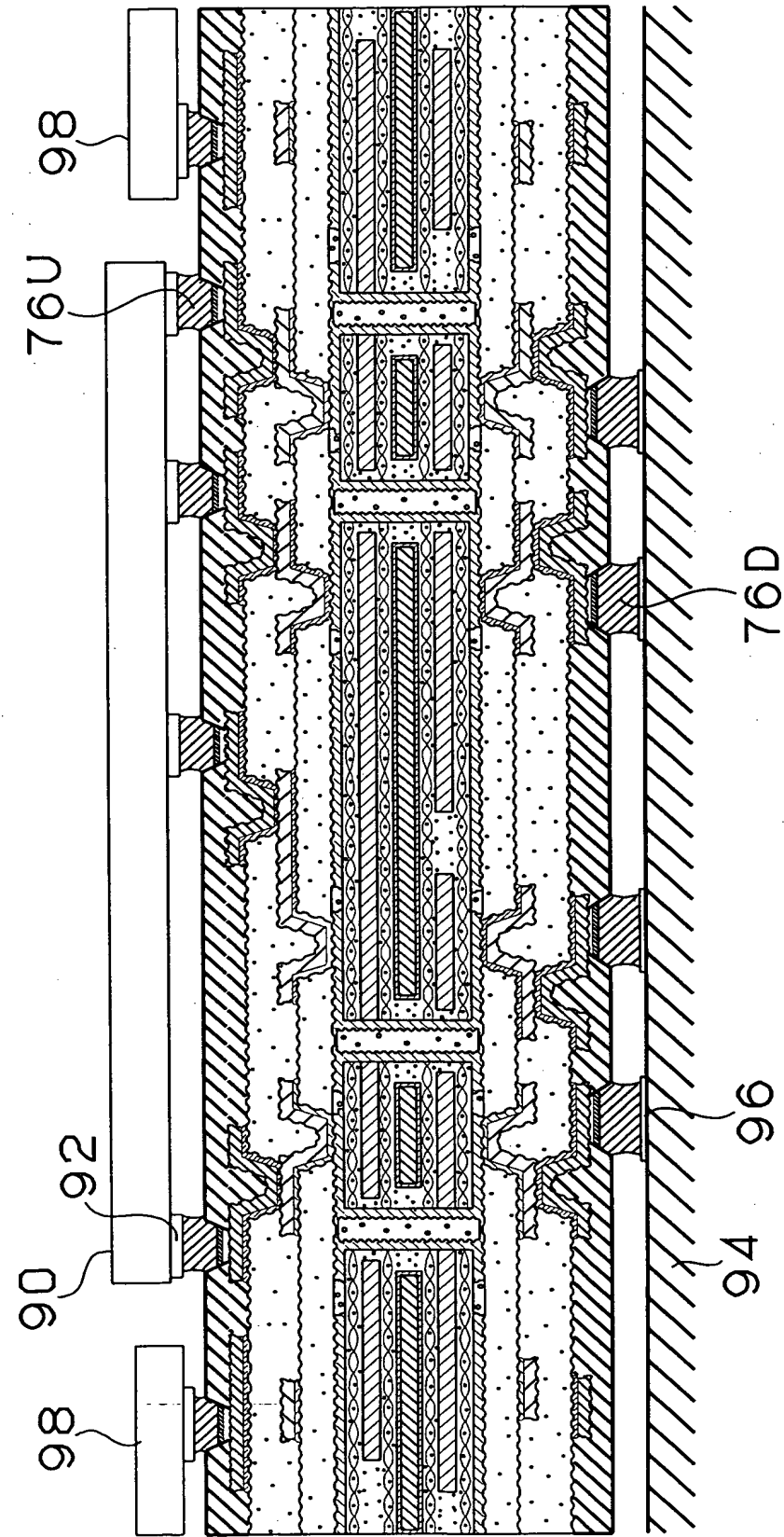


Fig. 19



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Fig. 20



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Fig. 21

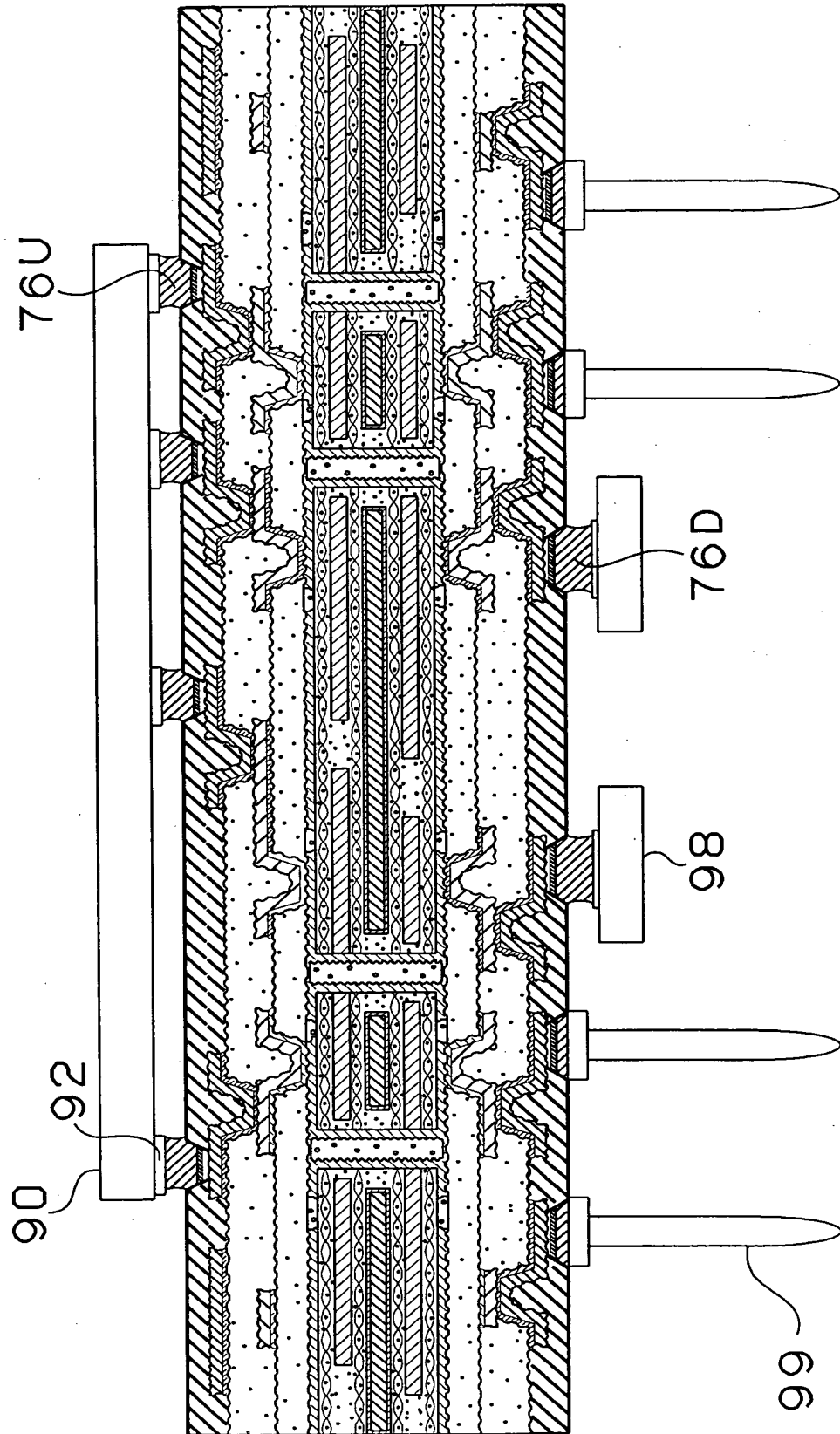
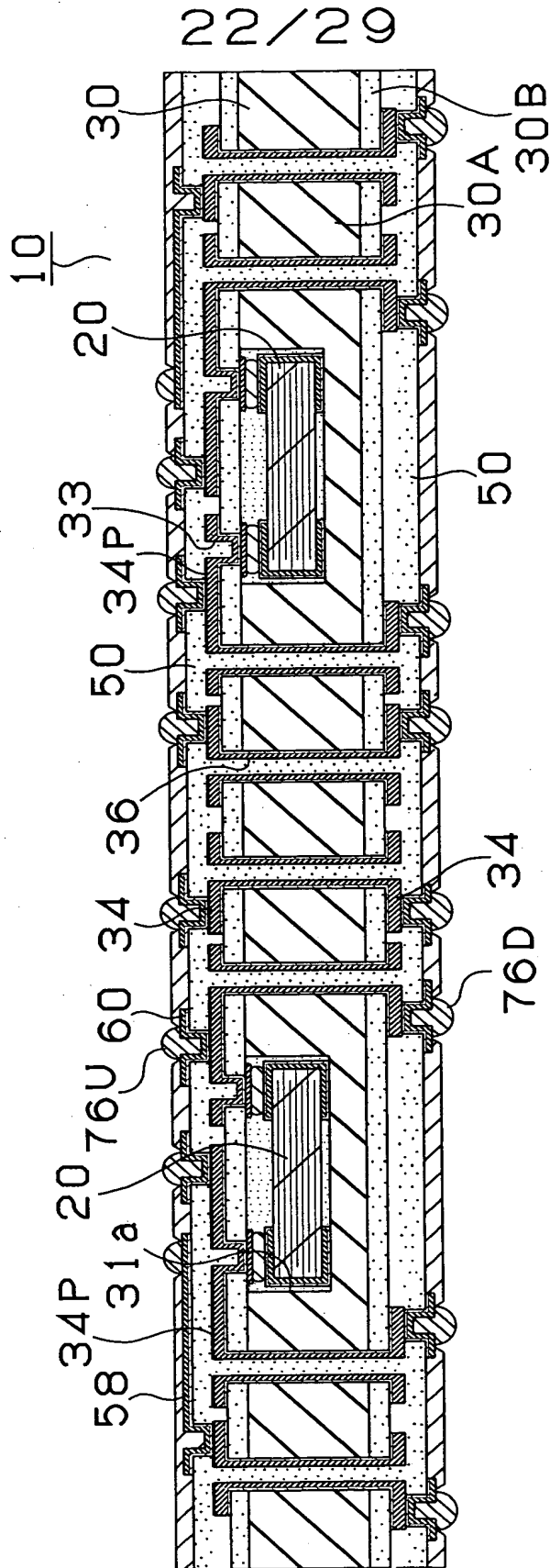
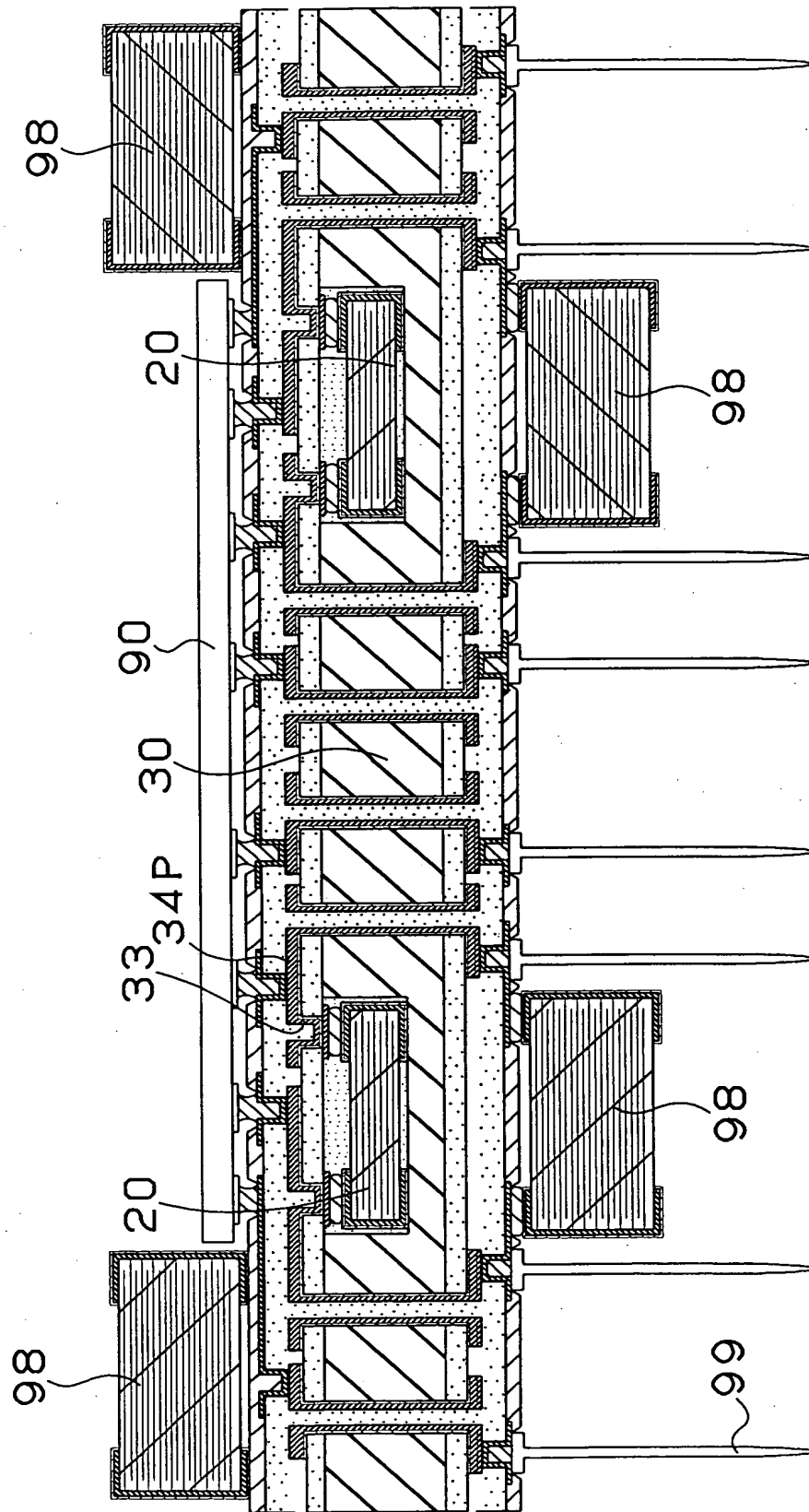


Fig. 22



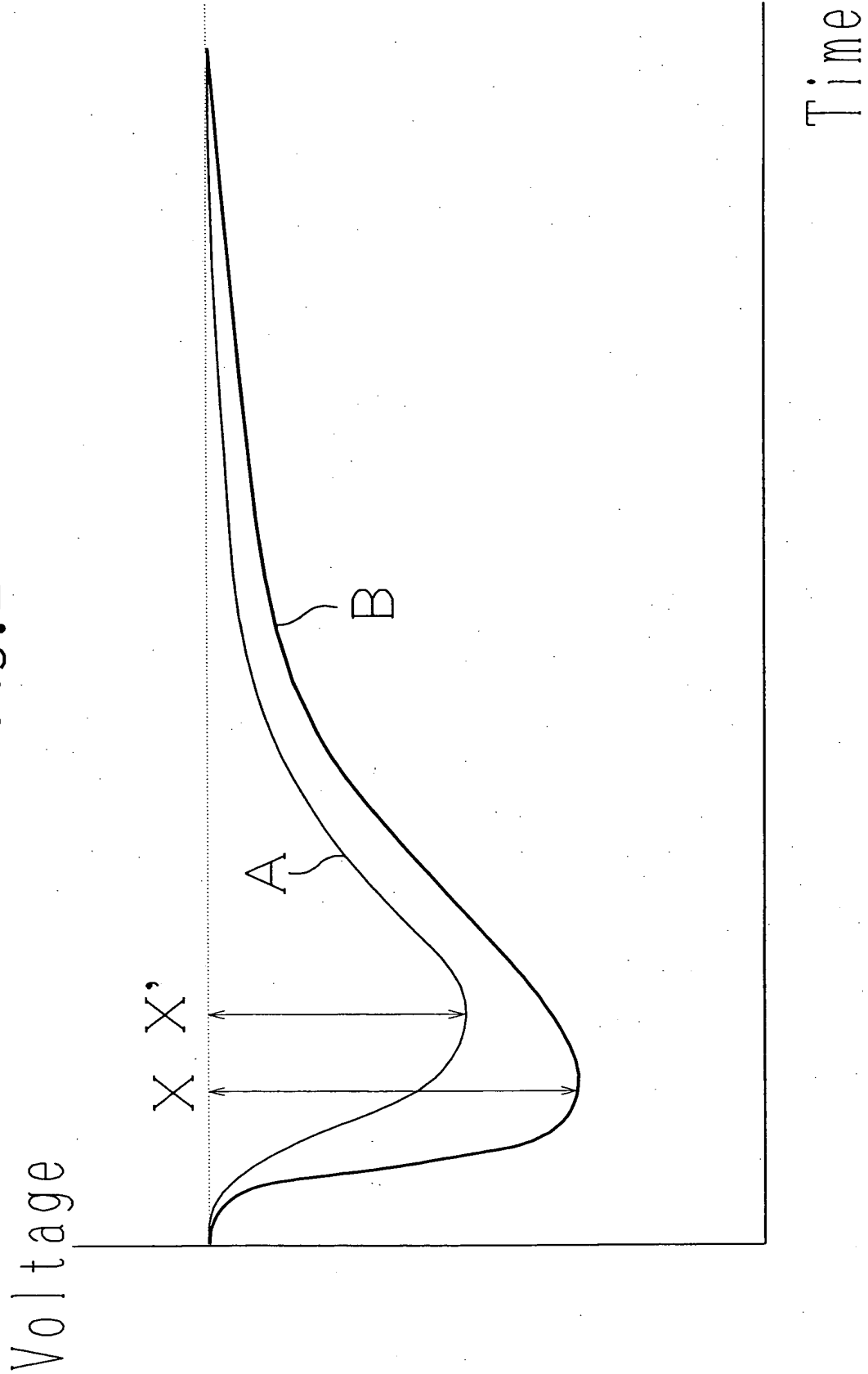
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Fig. 23



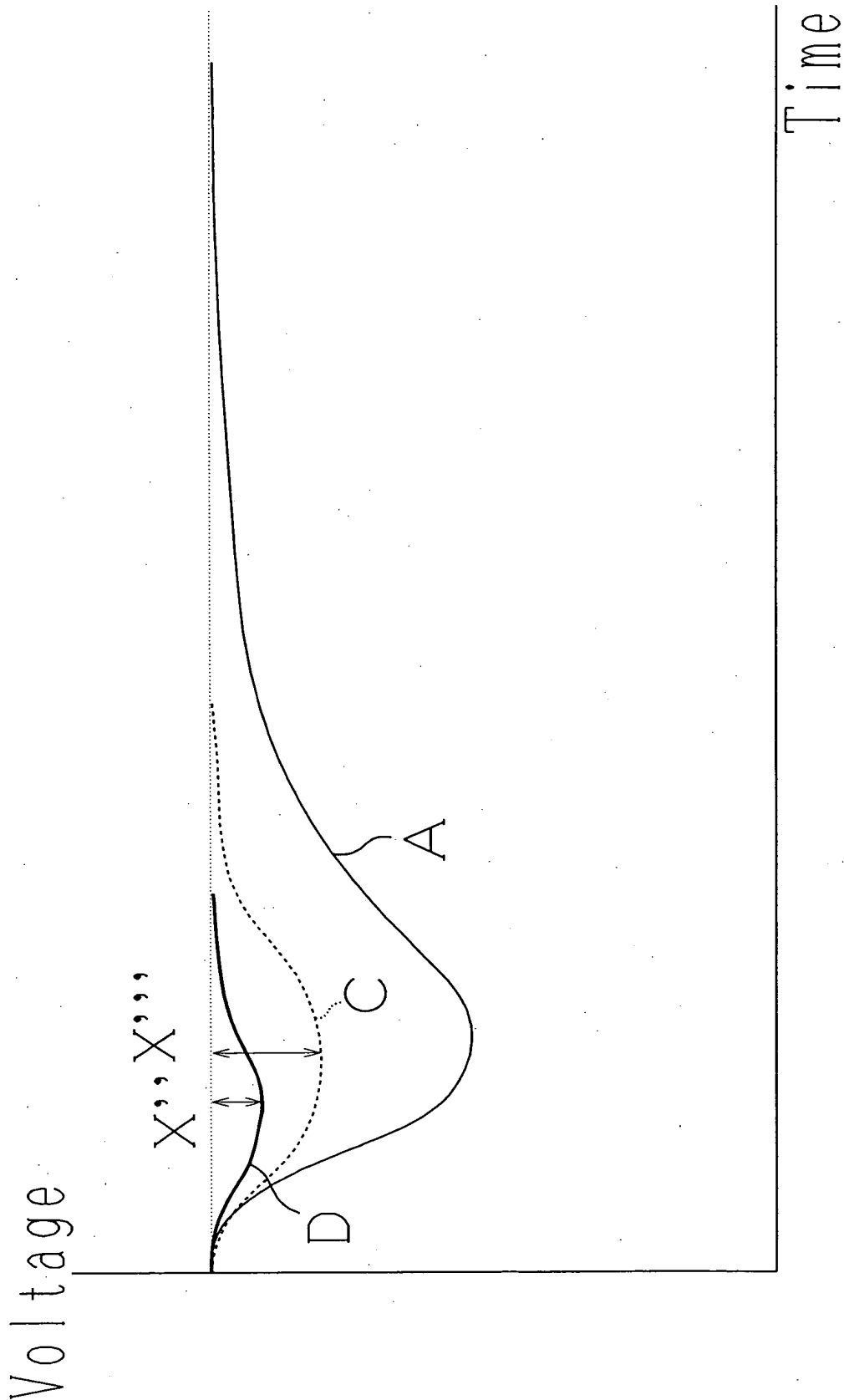
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Fig. 24



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Fig. 25



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Fig. 26

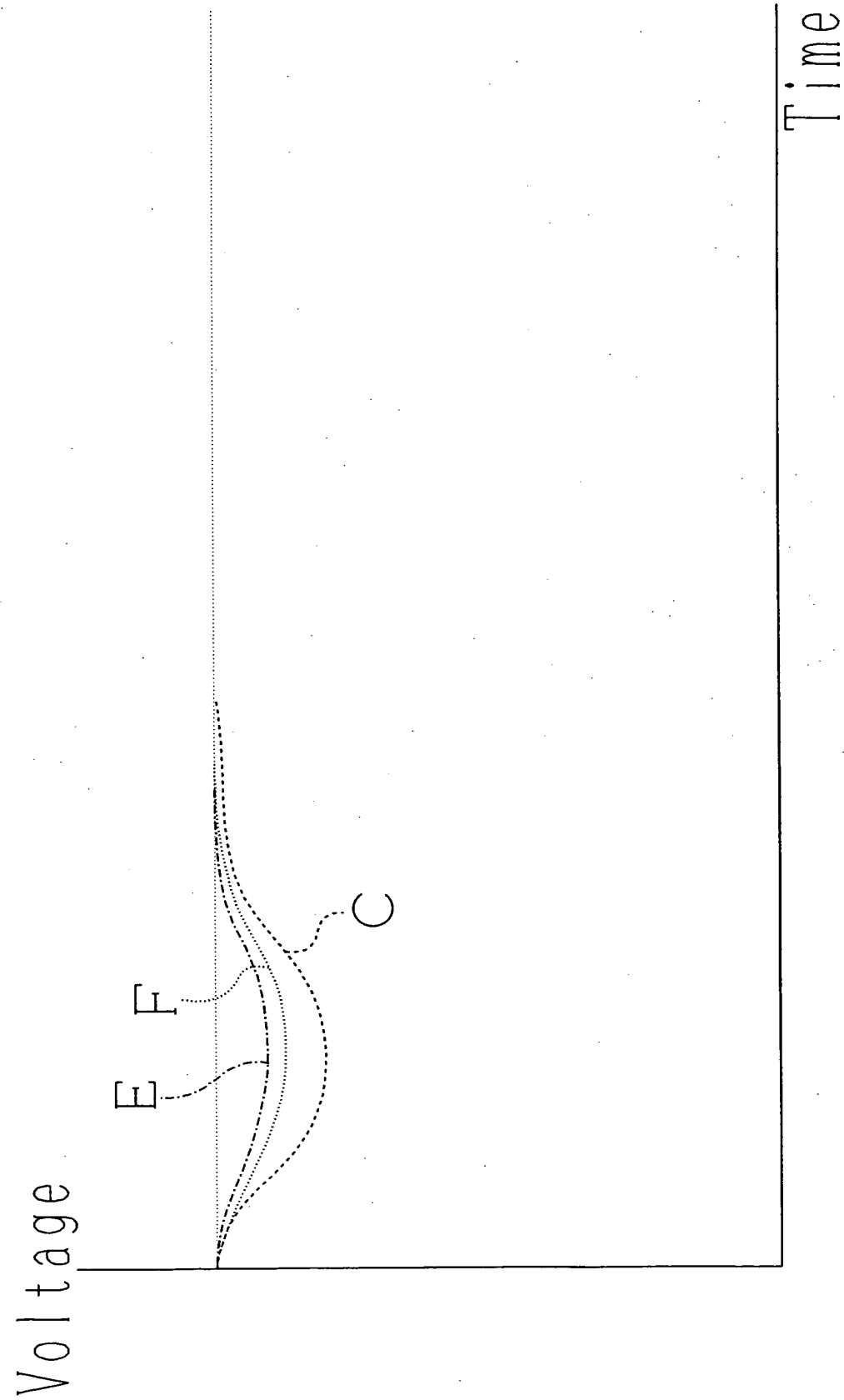


Fig. 27

[illegible]

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Fig. 28

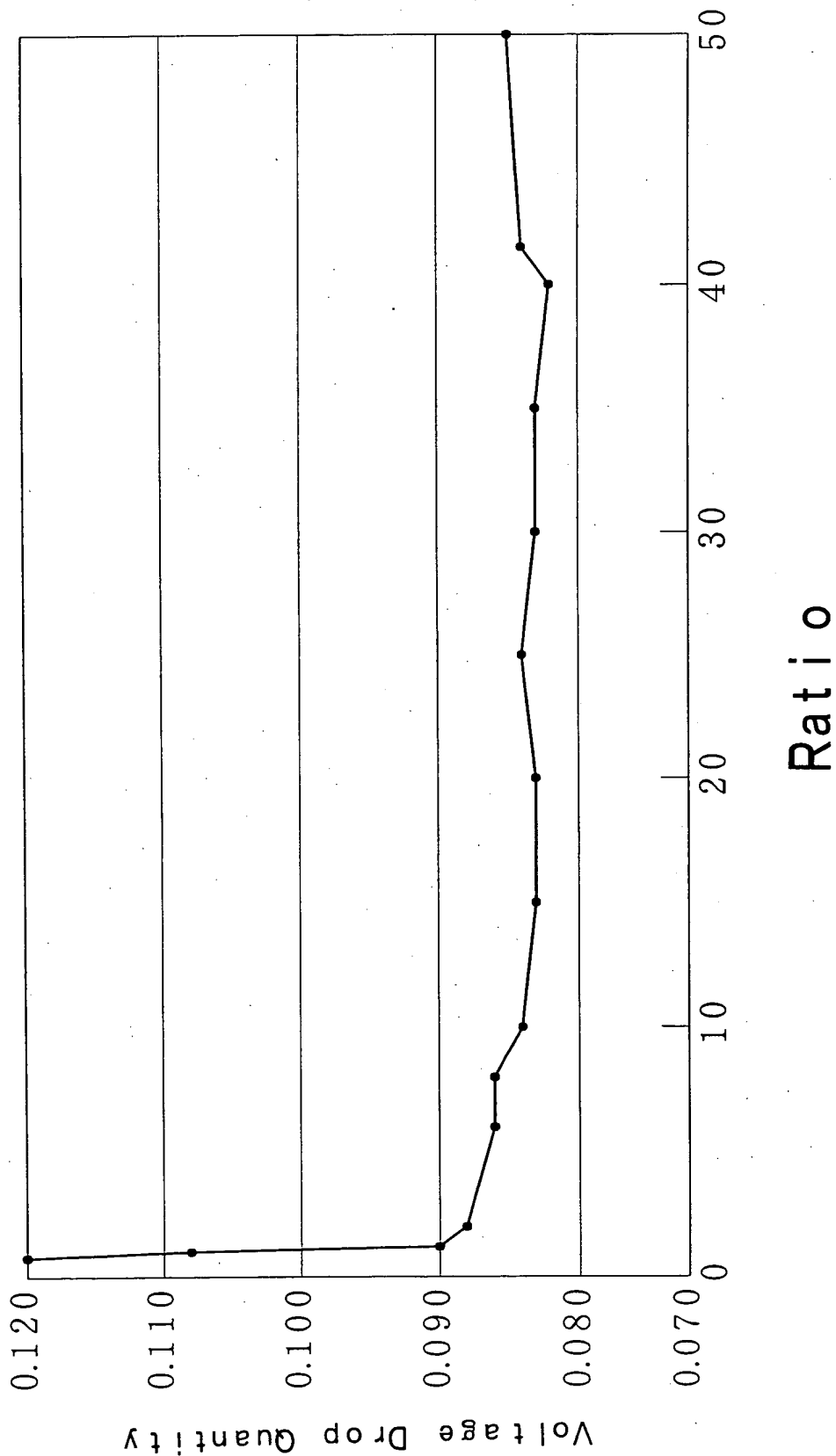
	Thickness of Conductor Circuit	100 hr		300 hr		500 hr		1000 hr		Voltage Drop Quantity
		Presence/Absence of Malfunction of IC	Presence/Absence of Open	Presence/Absence of Malfunction of IC	Presence/Absence of Open	Presence/Absence of Malfunction of IC	Presence/Absence of Open	Presence/Absence of Malfunction of IC	Presence/Absence of Open	
Embodiment 5-1	Ratio $\alpha 1 / \alpha 2$ 6.7	○	○	○	○	○	○	○	○	0.086
Embodiment 5-2	5.4	○	○	○	○	○	○	○	○	0.086
Embodiment 5-3	10.0	○	○	○	○	○	○	○	○	0.084
Embodiment 5-4	20.0	○	○	○	○	○	○	○	○	0.083
Embodiment 5-5	30.0	○	○	○	○	○	○	○	○	0.083
Embodiment 5-6	40.0	○	○	○	○	○	○	○	○	0.082
Embodiment 6-1	2.0	○	○	○	○	○	○	○	○	0.088
Embodiment 6-2	3.7	○	○	○	○	○	○	○	○	0.087
Embodiment 6-3	5.0	○	○	○	○	○	○	○	○	0.087
Embodiment 6-4	30.0	○	○	○	○	○	○	○	○	0.083
Comparison Example	1.0	×	○	×	○	×	×	×	×	0.108
Reference Example	41.5	○	○	○	○	○	○	○	×	0.084

Presence/Absence of Malfunction of IC, (○ : No Malfunction; × : Malfunction, Presence/Absence of Open, ○ : No Open, × : Open)

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Fig. 29

Core Power Supply Layer Ratio



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